

Voltage Detector IC Series

Free Delay Time Setting **CMOS Voltage Detector IC Series**

BD52xx series BD53xx series

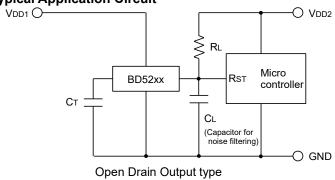
General Description

Rohm's BD52xx and BD53xx series are highly accurate, low current consumption Voltage Detector ICs with a capacitor-controlled time delay. The line up includes BD52xx devices with N channel open drain output and BD53xx devices with CMOS output. The devices are available for specific detection voltages ranging from 2.3V to 6.0V in increments of 0.1V.

Features

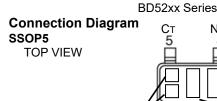
- Delay Time Controlled by external Capacitor
- Two output types (N channel open drain and CMOS
- Ultra-low current consumption
- Very small and low height package
- Package SSOP5 is similar to SOT-23-5(JEDEC)

Typical Application Circuit



N.C.

Lot. No



Marking

1 2

n Descri	Descriptions Vout VDD GND				
	SSOP5				
PIN No.	Symbol	Function			
1	Vout	Reset Output			
2	VDD	Power Supply Voltage			
3	GND	GND			
4	N.C.	Unconnected Terminal			
5	Ст	Capacitor connection terminal for output delay time			

Key Specifications

Detection voltage: 2.3V to 6.0V (Typ.)

0.1V steps

■ High accuracy detection voltage: ±1.0%

■ Ultra-low current consumption: 0.95µA (Typ.)

Package SSOP5:

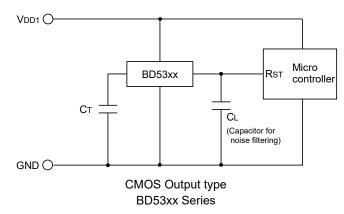
VSOF5:

W(typ) x D(typ) x H(max) 2.90mm x 2.80mm x 1.25mm

1.60mm x 1.60mm x 0.60mm

Applications

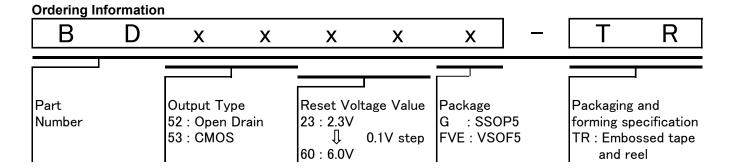
Circuits using microcontrollers or logic circuits that require a reset.



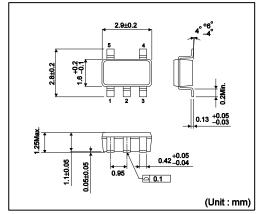
VSOF5		
TOP VIEW	VDD GND	
	5 4	
		>
Marki	-	Lot. No
	Vout SUB	Ст

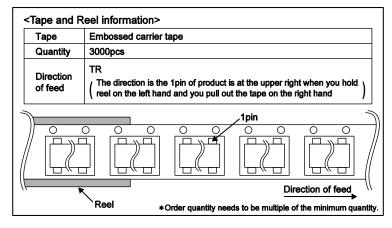
	VSOF5				
PIN No.	Symbol	Function			
1	Vout	Reset Output			
2	SUB	Substrate*			
3	Ст	Capacitor connection terminal for			
3	CT	output delay time			
4	GND	GND			
5	Vdd	Power Supply Voltage			

^{*}Connect the substrate to GND.

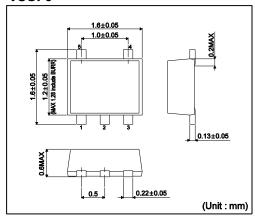


SSOP5





VSOF5



Lineup

Table 1. Lineup for SSOP5 Package

Package Type	SSOP5 Package SSOP5				
Output Type	(Open Drain		CMOS	
Detection Voltage	Marking	Part Number	Marking	Part Number	
6.0V	PW	BD5260	RW	BD5360	
5.9V	PV	BD5259	RV	BD5359	
5.8V	PU	BD5258	RU	BD5358	
5.7V	PT	BD5257	RT	BD5357	
5.6V	PS	BD5256	RS	BD5356	
5.5V	PR	BD5255	RR	BD5355	
5.4V	PQ	BD5254	RQ	BD5354	
5.3V	PP	BD5253	RP	BD5353	
5.2V	PN	BD5252	RN	BD5352	
5.1V	PM	BD5251	RM	BD5351	
5.0V	PL	BD5250	RL	BD5350	
4.9V	PK	BD5249	RK	BD5349	
4.8V	PJ	BD5248	RJ	BD5348	
4.7V	PH	BD5247	RH	BD5347	
4.6V	PG	BD5246	RG	BD5346	
4.5V	PF	BD5245	RF	BD5345	
4.4V	PE	BD5244	RE	BD5344	
4.3V	PD	BD5243	RD	BD5343	
4.2V	PC	BD5242	RC	BD5342	
4.1V	PB	BD5241	RB	BD5341	
4.0V	PA	BD5240	RA	BD5340	
3.9V	MV	BD5239	QV	BD5339	
3.8V	MU	BD5238	QU	BD5338	
3.7V	MT	BD5237	QT	BD5337	
3.6V	MS	BD5236	QS	BD5336	
3.5V	MR	BD5235	QR	BD5335	
3.4V	MQ	BD5234	QQ	BD5334	
3.3V	MP	BD5233	QP	BD5333	
3.2V	MN	BD5232	QN	BD5332	
3.1V	MM	BD5231	QM	BD5331	
3.0V	ML	BD5230	QL	BD5330	
2.9V	MK	BD5229	QK	BD5329	
2.8V	MJ	BD5228	QJ	BD5328	
2.7V	MH	BD5227	QH	BD5327	
2.6V	MG	BD5226	QG	BD5326	
2.5V	MF	BD5225	QF	BD5325	
2.4V	ME	BD5224	QE	BD5324	
2.3V	MD	BD5223	QD	BD5323	

Lineup - continued

Table 2. Lineup for VSOF5 Package

Package Type	VSOF5				
Output Type	(Open Drain		CMOS	
Detection Voltage	Marking	Part Number	Marking	Part Number	
6.0V	PW	BD5260	RW	BD5360	
5.9V	PV	BD5259	RV	BD5359	
5.8V	PU	BD5258	RU	BD5358	
5.7V	PT	BD5257	RT	BD5357	
5.6V	PS	BD5256	RS	BD5356	
5.5V	PR	BD5255	RR	BD5355	
5.4V	PQ	BD5254	RQ	BD5354	
5.3V	PP	BD5253	RP	BD5353	
5.2V	PN	BD5252	RN	BD5352	
5.1V	PM	BD5251	RM	BD5351	
5.0V	PL	BD5250	RL	BD5350	
4.9V	PK	BD5249	RK	BD5349	
4.8V	PJ	BD5248	RJ	BD5348	
4.7V	PH	BD5247	RH	BD5347	
4.6V	PG	BD5246	RG	BD5346	
4.5V	PF	BD5245	RF	BD5345	
4.4V	PE	BD5244	RE	BD5344	
4.3V	PD	BD5243	RD	BD5343	
4.2V	PC	BD5242	RC	BD5342	
4.1V	PB	BD5241	RB	BD5341	
4.0V	PA	BD5240	RA	BD5340	
3.9V	MV	BD5239	QV	BD5339	
3.8V	MU	BD5238	QU	BD5338	
3.7V	MT	BD5237	QT	BD5337	
3.6V	MS	BD5236	QS	BD5336	
3.5V	MR	BD5235	QR	BD5335	
3.4V	MQ	BD5234	QQ	BD5334	
3.3V	MP	BD5233	QP	BD5333	
3.2V	MN	BD5232	QN	BD5332	
3.1V	MM	BD5231	QM	BD5331	
3.0V	ML	BD5230	QL	BD5330	
2.9V	MK	BD5229	QK	BD5329	
2.8V	MJ	BD5228	QJ	BD5328	
2.7V	MH	BD5227	QH	BD5327	
2.6V	MG	BD5226	QG	BD5326	
2.5V	MF	BD5225	QF	BD5325	
2.4V	ME	BD5224	QE	BD5324	
2.3V	MD	BD5223	QD	BD5323	

The part number shown in red letters are "Not Recommended for New Designs".

Absolute maximum ratings

Parameter		Symbol	Limits	Unit	
Power Supply Volta	age	V_{DD} -GND	-0.3 to +10	V	
Nch Open Drain Output		\ <i>\</i>	GND-0.3 to +10	.,	
Output Voltage	CMOS Output	Vout	GND-0.3 to V _{DD} +0.3	V	
Output Current		lo	80	mA	
Power	SSOP5 *1*3	5	540	\^/	
Dissipation VSOF5 *2*3		Pd	210	mW	
Operating Temperature		Topr	-40 to +105	°C	
Ambient Storage Temperature		Tstg	-55 to +125	°C	

^{*1} Reduced by 5.4mW/°C when used over 25°C.

Electrical characteristics (Unless Otherwise Specified Ta=-40 to 105°C)

Parameter	Symbol		Condition		Limit		Unit
i arameter	Symbol		Condition	Min. VDET(T)	Тур.	Max.	Offic
		VDD=H→L, RL=47	VDD=H→L, RL=470kΩ ^{*1}		VDET(T)	VDET(T) ×1.01	
			Ta=+25°C	2.475	2.5	2.525	
		VDET=2.5V	Ta=-40°C to 85°C	2.418	-	2.584	
			Ta=85°C to 105°C	2.404	-	2.597	
			Ta=+25°C	2.970	3.0	3.030	
		VDET=3.0V	Ta=-40°C to 85°C	2.901	-	3.100	
			Ta=85°C to 105°C	2.885	-	3.117	
Detection Voltage	V _{DET}		Ta=+25°C	3.267	3.3	3.333	V
201001011	1021	VDET=3.3V	Ta=-40°C to 85°C	3.191	-	3.410	•
			Ta=85°C to 105°C	3.173	-	3.428	
			Ta=+25°C	4.158	4.2	4.242	
		VDET=4.2V	Ta=-40°C to 85°C	4.061	-	4.341	
			Ta=85°C to 105°C	4.039	-	4.364	
			Ta=+25°C	4.752	4.8	4.848	
		VDET=4.8V	Ta=-40°C to 85°C	4.641	-	4.961	
			Ta=85°C to 105°C	4.616	-	4.987	
		VDD=VDET-0.2V	V _{DET} =2.3-3.1V	-	0.80	2.40	μΑ
0: ::0	14		V _{DET} =3.2-4.2V	-	0.85	2.55	
Circuit Current when ON	IDD1		V _{DET} =4.3-5.2V	-	0.90	2.70	
			V _{DET} =5.3-6.0V	-	0.95	2.85	
			V _{DET} =2.3-3.1V	-	0.75	2.25	
Cinavit Comment when OFF	InnO	\/pp=\/p=+.0.0\/	V _{DET} =3.2-4.2V	-	0.80	2.40	μA
Circuit Current when OFF	IDD2	VDD=VDET+2.0V	V _{DET} =4.3-5.2V	-	0.85	2.55	
			$V_{DET} = 5.3-6.0V$	-	0.90	2.70	
Operating Valtage Bange	Von	VoL≤0.4V, Ta=25 t	to 105°C, RL=470kΩ	0.95	-	-	V
Operating Voltage Range	VOPL	VoL≤0.4V, Ta=-40 to 25°C, RL=470kΩ		1.20	-	-	V
1 ow' Output Voltage (Nah)	Vol	$V_{DD}=1.2V$, ISINK = 0	.4 mA, VDET=2.3-6.0V	-	-	0.5	V
Low' Output Voltage (Nch)	VOL	VDD=2.4V, ISINK = 2	.0 mA, VDET=2.7-6.0V	-	-	0.5	V
		VDD=4.8V, ISOURCE	=0.7 mA, VDET(2.3V to 4.2V)	VDD-0.5	-	-	
'High' Output Voltage (Pch)	Vон	VDD=6.0V, ISOURCE	VDD=6.0V, ISOURCE=0.9 mA, VDET(4.3V to 5.2V)		-	-	V
		VDD=8.0V, ISOURCE	=1.1 mA, VDET(5.3V to 6.0V)	VDD-0.5	-	_	

VDET (T): Standard Detection Voltage (2.3V to 6.0V, 0.1V step)

R_L: Pull-up resistor to be connected between VouT and power supply. Design Guarantee. (Outgoing inspection is not done on all products.)

*1 Guaranteed at Ta=25°C.

^{*2} Reduced by 2.1mW/°C when used over 25°C.

^{*3} When mounted on ROHM standard circuit board (70mm×70mm×1.6mm, glass epoxy board).

Electrical characteristics (Unless Otherwise Specified Ta=-40 to 105°C) - continued

Davamatav	C. mahal	Condition		Limit		Linit
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Leak Current	I _{leak}	VDD=VDS=10V *1	-	-	0.1	μA
		VDD=VDET×1.1, VDET=2.3-2.6V, RL=470kΩ	VDD ×0.30	VDD ×0.40	VDD ×0.60	
		Von=Von=x4.4. Von==2.7.4.2V Dr =470k0	VDD	Vdd	VDD	
	VDD=VDET×1.1, VDET=2.7-4.2V, RL=470kΩ	×0.30	×0.45	×0.60		
C _T pin Threshold Voltage	Vстн	VCTH $VDD=VDET\times1.1$, $VDET=4.3-5.2V$, $RL=470k\Omega$	VDD	Vdd	VDD	V
		VDD=VDE1×1.1, VDE1-4.3-3.2V, RL-470KΩ	×0.35	×0.50	×0.60	
		VDD=VDET×1.1, VDET=5.3-6.0V, RL=470kΩ	VDD	Vdd	VDD	
		VDD-VDE1*1.1, VDE1-3.3-0.0V, RL-470K22	×0.40	×0.50	×0.60	
Output Delay Resistance	Rct	VDD=VDET×1.1 VCT=0.5V *1	5.5	9	12.5	МΩ
C- nin Outnut Current	lot	VCT=0.1V VDD=0.95V *1	15	40	-	
C _T pin Output Current ICT		VCT=0.5V VDD=1.5V	150	240	-	μA
Detection Voltage Temperature coefficient	VDET/ΔT	Ta=-40°C to 105°C	-	±100	±360	ppm/°C
Hysteresis Voltage	Δ VDET	V _{DD} =L→H→L, R _L =470kΩ	VDET ×0.03	VDET ×0.05	VDET ×0.08	V
				^U.U3 ~U.U3 ~U.	^0.00	,

VDET (T): Standard Detection Voltage (2.3V to 6.0V, 0.1V step)
R_L: Pull-up resistor to be connected between Vo∪T and power supply.
Design Guarantee. (Outgoing inspection is not done on all products.)
*1 Guaranteed at Ta=25°C.

Block Diagrams

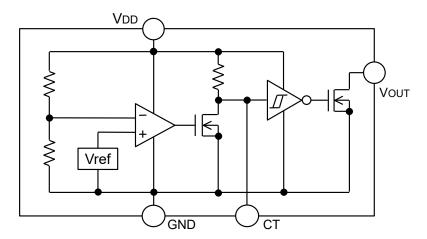


Fig.1 BD52xx Series

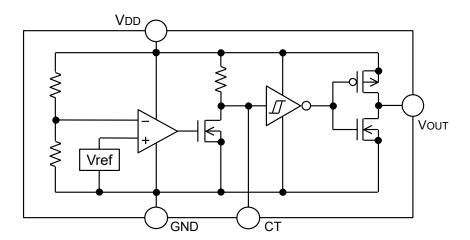


Fig.2 BD53xx Series

Typical Performance Curves

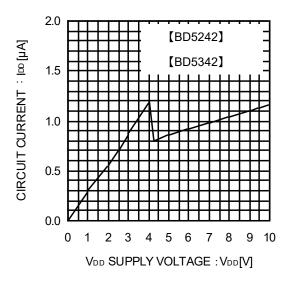


Fig.3 Circuit Current

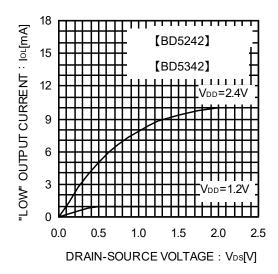


Fig.4 "Low" Output Current

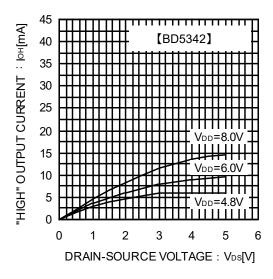


Fig.5 "High" Output Current

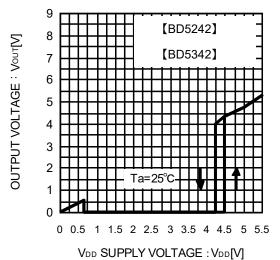


Fig.6 I/O Characteristics

Typical Performance Curves - continued

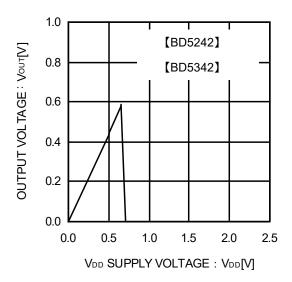


Fig.7 Operating Limit Voltage

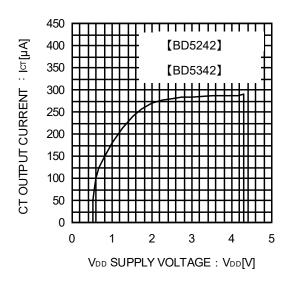


Fig.8 CT Terminal Current

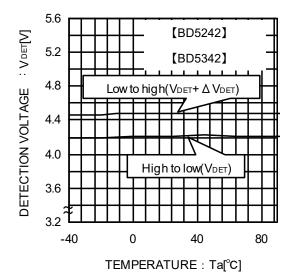


Fig.9 Detection Voltage Release Voltage

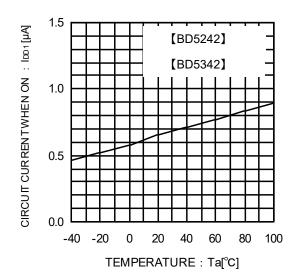


Fig.10 Circuit Current when ON

Typical Performance Curves - continued

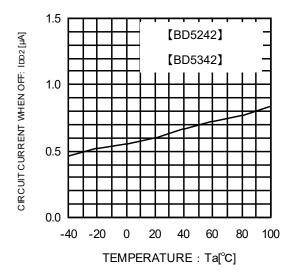


Fig.11 Circuit Current when OFF

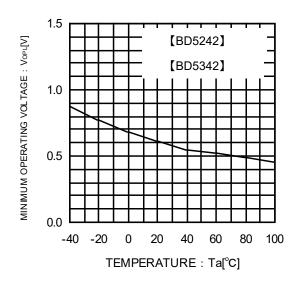


Fig.12 Operating Limit Voltage

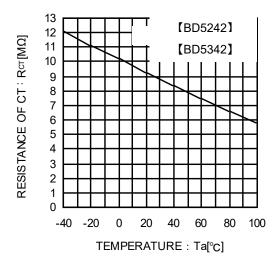


Fig.13 CT Terminal Circuit Resistance

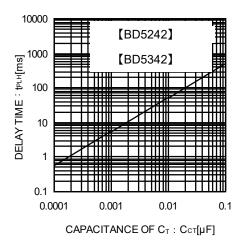


Fig.14 Delay Time (t_{PLH}) and C_T Terminal External Capacitance

Application Information

Explanation of Operation

For both the open drain type (Fig.15) and the CMOS output type (Fig.16), the detection and release voltages are used as threshold voltages. When the voltage applied to the V_{DD} pins reaches the applicable threshold voltage, the V_{OUT} terminal voltage switches from either "High" to "Low" or from "Low" to "High". Please refer to the Timing Waveform and Electrical Characteristics for information on hysteresis. Because the BD52xx series uses an open drain output type, it is necessary to connect a pull-up resistor to V_{DD} or another power supply if needed [The output "High" voltage (V_{OUT}) in this case becomes V_{DD} or the voltage of the other power supply].

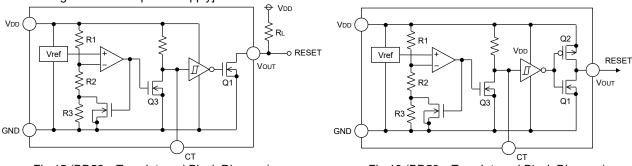


Fig.15 (BD52xxType Internal Block Diagram)

Fig.16 (BD53xxType Internal Block Diagram)

Setting of Detector Delay Time

It is possible to set the delay time at the rise of VDD using a capacitor connected to the Ct terminal.

Delay time at the rise of V_{DD} t_{PLH}: Time until when Vout rise to 1/2 of V_{DD} after V_{DD} rise up and beyond the release voltage($V_{DET} + \Delta V_{DET}$)

$$t_{PLH} = -C_{CT} \times R_{CT} \times In \left(\frac{V_{DD} - V_{CTH}}{V_{DD}} \right)$$

C_{CT}: C_T pin External Capacitance

R_{CT}: C_T pin Internal Impedance (Please refer to Electrical Characteristics.)

V_{CTH}: C_T pin Threshold Voltage (Please refer to Electrical Characteristics.)

In: Natural Logarithm

Reference Data of Falling Time (tphl) Output

Examples of Falling Time (tPHL) Output

Part Number	Part Number t _{PHL} [µs] -40°C		t _{РНL} [µs],+105°С
BD5227	30.8	30	28.8
BD5327	26.8	26	24.8

^{*}This data is for reference only.

The figures will vary with the application, so please confirm actual operating conditions before use.

Timing Waveforms

Example: the following shows the relationship between the input voltage VDD, the C_T Terminal Voltage VCT and the output voltage VOUT when the input power supply voltage VDD is made to sweep up and sweep down (The circuits are those in Figure.15 and 16).

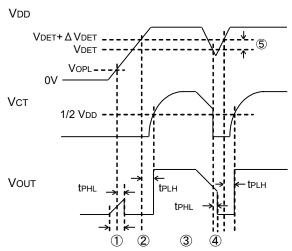


Fig.17 Timing Waveform

- ① When the power supply is turned on, the output is unstable from after over the operating limit voltage (VoPL) until tPHL. Therefore it is possible that the reset signal is not outputted when the rise time of V_{DD} is faster than tPHL.
- ② When VDD is greater than VOPL but less than the reset release voltage (VDET+ Δ VDET), the C_T terminal (VCT) and output (VOUT) voltages will switch to L.
- ③ If VDD exceeds the reset release voltage (VDET+ Δ VDET), then VOUT switches from L to H (with a delay due to the C_T terminal).
- ④ If VDD drops below the detection voltage (VDET) when the power supply is powered down or when there is a power supply fluctuation, VOUT switches to L (with a delay of tPHL).
- $^{\circ}$ The potential difference between the detection voltage and the release voltage is known as the hysteresis width (Δ VDET). The system is designed such that the output does not toggle with power supply fluctuations within this hysteresis width, preventing malfunctions due to noise.

Circuit Applications

1) Examples of a common power supply detection reset circuit

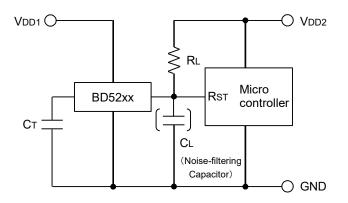


Fig.18 Open Drain Output Type

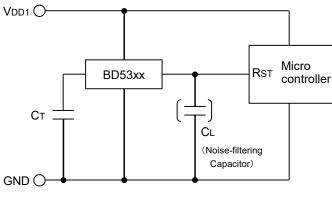


Fig.19 CMOS Output Type

Application examples of BD52xx series (Open Drain output type) and BD53xx series (CMOS output type) are shown below.

CASE1: Power supply of the microcontroller (V_{DD2}) differs from the power supply of the reset detection (V_{DD1}).

Use an open drain output type (BD52xx) device with a load resistance R_L attached as shown Fig.18.

CASE2: Power supply of the microcontroller (V_{DD1}) is the same as the power supply of the reset detection (V_{DD1}). Use a CMOS output type (BD53xx) device or an open drain output type (BD52xx) device with a pull up resistor between the output and V_{DD1} .

When a capacitance C_L for noise filtering is connected to the V_{OUT} pin (the reset signal input terminal of the microcontroller), please take into account the waveform of the rise and fall of the output voltage (V_{OUT}).

Please refer to Operational Notes for recommendations on resistor and capacitor values.

2) The following is an example of a circuit application in which an OR connection between two types of detection voltage resets the microcontroller.

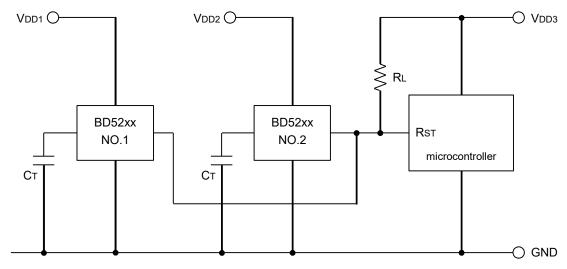


Fig.20 OR Circuit Connection Application

To reset the microcontroller when many independent power supplies are used in the system, OR connect an open drain output type (BD52xx series) to the microcontroller's input with pull-up resistor to the supply voltage of the microcontroller (V_{DD3}) as shown in Fig. 20. By pulling-up to V_{DD3}, output "High" voltage of micro-controller power supply is possible.

3) Examples of the power supply with resistor dividers

In applications wherein the power supply voltage of an IC comes from a resistor divider circuit, an in-rush current will flow into the circuit when the output level switches from "High" to "Low" or vice versa. In-rush current is a sudden surge of current that flows from the power supply (VDD) to ground (GND) as the output logic changes its state. This current flow may cause malfunction in the systems operation such as output oscillations, etc.

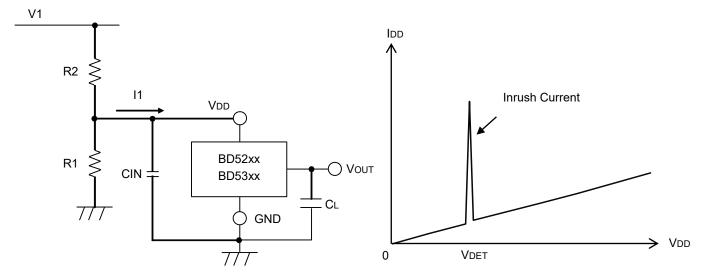


Fig.21 Resistor Divider Connection Application

When an in-rush current (I1) flows into the circuit (Refer to Fig. 21) at the time when output switches from "Low" to "High", a voltage drop of I1×R2 (input resistor) will occur in the circuit causing the VDD supply voltage to decrease. When the VDD voltage drops below the detection voltage, the output will switch from "High" to "Low". While the output voltage is at "Low" condition, in-rush current will stop flowing and the voltage drop will be reduced. As a result, the output voltage will switches again from "Low" to "High" which causes an in-rush current and a voltage drop. This operation repeats and will result to oscillation.

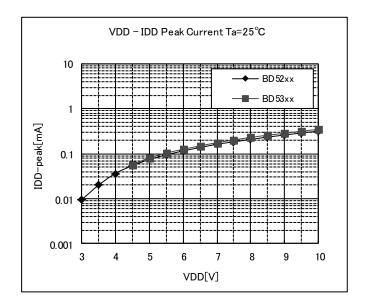


Figure.22 IDD Peak Current vs. Power Supply Voltage

The figures will vary with the application, so please confirm actual operating conditions before use.

^{*} This data is for reference only.

Operational Notes

1) Absolute maximum ratings

Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

2) Ground Voltage

The voltage of the ground pin must be the lowest voltage of all pins of the IC at all operating conditions. Ensure that no pins are at a voltage below the ground pin at any time, even during transient condition.

3) Recommended operating conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

4) Bypass Capacitor for Noise Rejection

To help reject noise, put a 1µF capacitor between VDD pin and GND and 1000pF capacitor between VOUT pin and GND. Be careful when using extremely big capacitor as transient response will be affected.

5) Short between pins and mounting errors

Be careful when mounting the IC on printed circuit boards. The IC may be damaged if it is mounted in a wrong orientation or if pins are shorted together. Short circuit may be caused by conductive particles caught between the pins.

6) Operation under strong electromagnetic field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

- 7) The V_{DD} line impedance might cause oscillation because of the detection current.
- 8) A V_{DD} to GND capacitor (as close connection as possible) should be used in high V_{DD} line impedance condition.
- 9) Lower than the mininum input voltage puts the VouT in high impedance state, and it must be VDD in pull up (VDD) condition.

10) External parameters

The recommended value of R_L Resistor is $50k\Omega$ to $1M\Omega$. The recommended value of C_T Capacitor is over 100pF to 0.1 μ F. There are many factors (board layout, etc) that can affect characteristics. Please verify and confirm using practical applications.

11) Power on reset operation

Please note that the power on reset output varies with the V_{DD} rise time. Please verify the behavior in the actual operation.

12) Testing on application boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

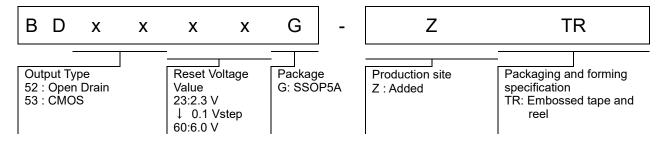
13) Rush current

When power is first supplied to the IC, rush current may flow instantaneously. It is possible that the charge current to the parasitic capacitance of internal photo diode or the internal logic may be unstable. Therefore, give special consideration to power coupling capacitance, power wiring, width of GND wiring, and routing of connections.

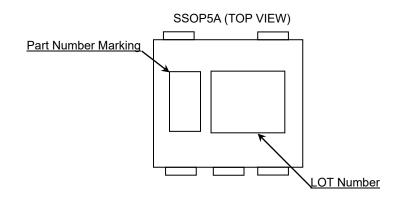
14) C_T pin discharge

Due to the capabilities of the C_T pin discharge transistor, the C_T pin may not completely discharge when a short input pulse is applied, and in this case the delay time may not be controlled. Please verify the actual operation.

Ordering Information



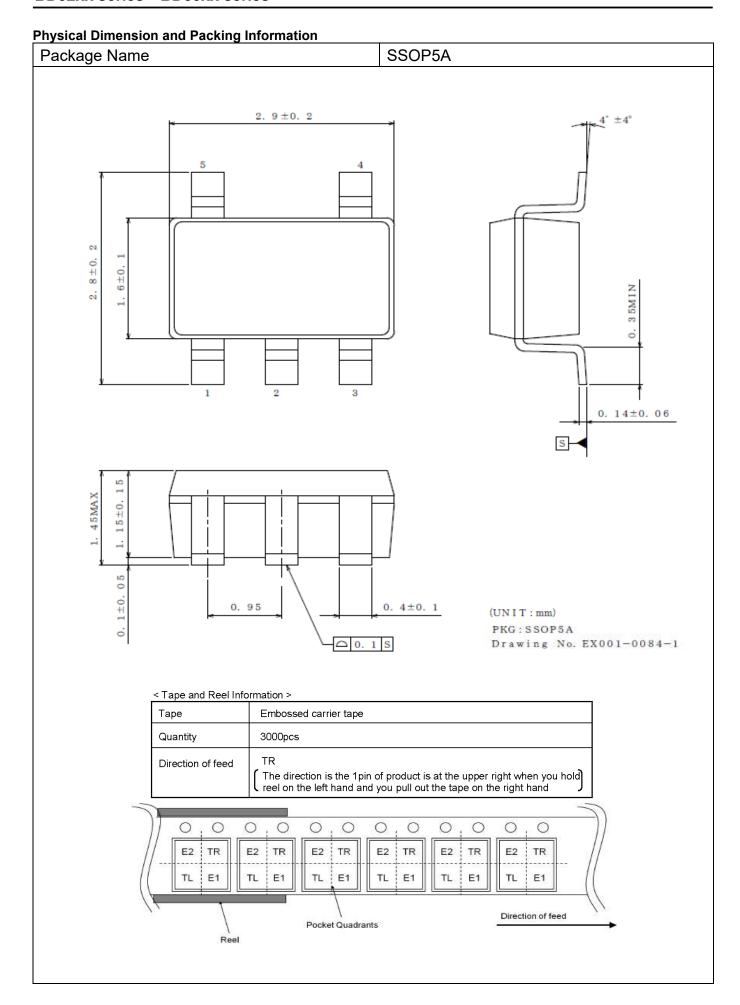
Marking Diagram



Output Type	Open Drain			CMOS
Detection Voltage	Marking	Marking Part Number Marking Part Nu		Part Number
6.0V	PW	BD5260	RW	BD5360
5.9V	PV	BD5259	RV	BD5359
5.8V	PU	BD5258	RU	BD5358
5.7V	PT	BD5257	RT	BD5357
5.6V	PS	BD5256	RS	BD5356
5.5V	PR	BD5255	RR	BD5355
5.4V	PQ	BD5254	RQ	BD5354
5.3V	PP	BD5253	RP	BD5353
5.2V	PN	BD5252	RN	BD5352
5.1V	PM	BD5251	RM	BD5351
5.0V	PL	BD5250	RL	BD5350
4.9V	PK	BD5249	RK	BD5349
4.8V	PJ	BD5248	RJ	BD5348
4.7V	PH	BD5247	RH	BD5347
4.6V	PG	BD5246	RG	BD5346
4.5V	PF	BD5245	RF	BD5345
4.4V	PE	BD5244	RE	BD5344
4.3V	PD	BD5243	RD	BD5343
4.2V	PC	BD5242	RC	BD5342
4.1V	PB	BD5241	RB	BD5341
4.0V	PA	BD5240	RA	BD5340

Marking Diagram - continued

Output Type	Open Drain			CMOS
Detection Voltage	Marking	Part Number	Marking	Part Number
3.9V	MV	BD5239	QV	BD5339
3.8V	MU	BD5238	QU	BD5338
3.7V	MT	BD5237	QT	BD5337
3.6V	MS	BD5236	QS	BD5336
3.5V	MR	BD5235	QR	BD5335
3.4V	MQ	BD5234	QQ	BD5334
3.3V	MP	BD5233	QP	BD5333
3.2V	MN	BD5232	QN	BD5332
3.1V	MM	BD5231	QM	BD5331
3.0V	ML	BD5230	QL	BD5330
2.9V	MK	BD5229	QK	BD5329
2.8V	MJ	BD5228	QJ	BD5328
2.7V	MH	BD5227	QH	BD5327
2.6V	MG	BD5226	QG	BD5326
2.5V	MF	BD5225	QF	BD5325
2.4V	ME	BD5224	QE	BD5324
2.3V	MD	BD5223	QD	BD5323



Revision History

Date	Revision	Changes
11.Oct.2021	009	Added "Revision History". Added words for Not Recommended New Designs category product.

Notice

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Our Products are designed and manufactured for application in ordinary electronic equipment (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSIII
CLASSIV		CLASSⅢ	

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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

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